

# Brightening the Future

## Financial Results of FY2024 Third-Quarter

From April 1, 2024 to December 31, 2024

SHINKO ELECTRIC INDUSTRIES CO., LTD.



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#### **Financial Results**

	FY2023	FY2024	Y	ΌΥ
	3rd-Quarter*1 (Results)	3rd-Quarter*1 (Results)	Amount	Ratio of Change
Net Sales	156.6	159.9	+3.3	+2%
Operating Profit (Ratio against Net Sales)	18.0 (11%)	19.1 (12%)	+1.1	+6%
Ordinary Profit (Ratio against Net Sales)	19.7 (13%)	19.1 (12%)	-0.6	-3%
Profit* <sup>2</sup> (Ratio against Net Sales)	13.4 (9%)	13.6 (9%)	+0.2	+2%

<sup>\*1</sup> Nine months ended December 31 \*2 Profit attributable to owners of parent

Earnings per Share	99.04yen	100.64yen
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#### **Summary of Financial Statements**

- As for the semiconductor industry, demand for AI continued to grow, and the semiconductor manufacturing equipment market remained strong mainly for capital investment for AI. On the other hand, tough market conditions continued, in which the semiconductor industry as a whole continued to be unable to achieve a full-fledged recovery, as demand for general-purpose servers, automobiles, and industrial equipment, etc. remained sluggish, and the industry was affected by prolonged inventory adjustments and other factors.
- As for the Shinko Group, orders of ceramic electrostatic chucks increased for semiconductor manufacturing equipment, and net sales of IC assemblies increased for high-end smartphones, etc. On the other hand, net sales of flip-chip type packages decreased due to the impact of delay in demand recovery for servers as well as intensified competition for PCs and other factors.
- Net sales up 2% year on year. Ordinary profit down 3% year on year due to lower sales of flip chip type packages and other factors. Profit up 2% year on year.



#### Net Sales and Ordinary Profit by Business Segment

		3rd-Qເ	2023 Jarter*1 Sults)	FY20 3rd-Qua (Resi	arter*1	Ratio of Change (YoY)
	Plastic Packages	96.5	Represent % of Net Sales [62%]	92.0	Represent % of Net Sales [58%]	- 5%
Sales	Metal Packages	54.1	[34%]	61.4	[38%]	+14%
Net	Others	6.1	[4%]	6.5	[4%]	+7%
	Total	156.6	[100%]	159.9	[100%]	+2%
ofit *3	Plastic Packages	9.2	Ratio against Net Sales (10%)	5.1	Ratio against Net Sales (6%)	-45%
γ Pr	Metal Packages	11.6	(21%)	14.8	(24%)	+28%
Ordinary Profit	Others/Adjustment	-1.1		-0.7		
o	Total	19.7	(13%)	19.1	(12%)	-3%

	ons or yen,
FY2	.023
127.8	Represent % of Net Sales [61%]
73.9	[35%]
8.3	[4%]
210.0	[100%]
11.8	Ratio against Net Sales (9%)
16.1	(22%)
-0.7	
27.3	(13%)

<sup>\*3</sup> Before inter-segment transaction adjustment



<sup>\*1</sup> Nine months ended December 31

<sup>\*2</sup> Sales to external customers

#### Financial Status, Capital Expenditure and Depreciation

	FY2023 3rd-Quarter*1	FY2024 3rd-Quarter*1
Total Assets	378.2	386.2
Net Assets	258.5	279.1
Equity Ratio	68%	72%

FY2023
393.8
265.0
67%

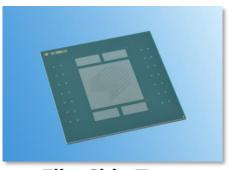
	FY2023 3rd-Quarter* <sup>2</sup>	FY2024 3rd-Quarter* <sup>2</sup>
Capital Expenditure * 3	28.2	15.4
Depreciation * 3	19.9	19.2
Research and Development	2.6	3.1
Exchange Rates (Yen/US dollar)	141	150

FY20	23
	63.7
	27.4
	3.5
	143

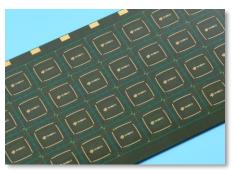
<sup>\*1</sup> As of December 31 \*2 Nine months ended December 31 \*3 Except intangible assets



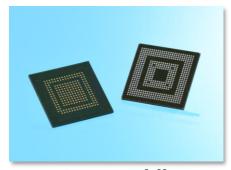
#### **Plastic Packages**



Flip-Chip Type Package



Plastic BGA Substrates



**IC Assemblies** 

#### [Applications]

PCs, Servers, Smartphones, Consumer Products, etc.

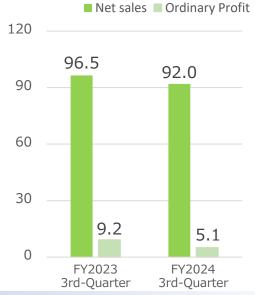


#### **Plastic Packages**

	FY2023	FY2024	Yo	Υ
	3rd-Quarter*1 (Results)	3rd-Quarter* <sup>1</sup> (Results)	Amount	Ratio of Change
Net Sales	96.5 [62%]*2	92.0 [58%]*2	-4.5	-5%
Ordinary Profit	9.2 (10%)*3	5.1 (6%)*3	-4.2	-45%

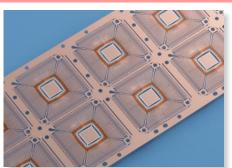
<sup>\*1</sup> Nine months ended December 31 \*2 Represent % of Net Sales \* 3 Ratio against Net Sales

- Net sales of flip-chip type packages decreased due to the impact of delay in demand recovery for servers as well as intensified competition for PCs and other factors.
- Net sales of IC assemblies increased for high-end smartphones, etc.
- Net sales of plastic BGA substrates were at almost the same level as the previous fiscal year due to the progress of yen depreciation in the exchange rate and other factors despite the impact of inventory adjustments in advanced memory, etc.

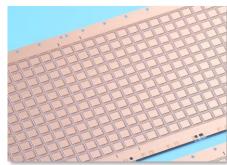




#### **Metal Packages**



**Stamped Leadframes** 



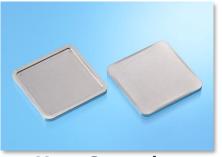
Etched Leadframes (OFN-Type)



Ceramic Electrostatic Chuck



**Glass-to-Metal Seals** 



**Heat Spreaders** 

#### [Applications]

Automobiles, Smartphones, Consumer Products, Semiconductor Manufacturing Equipment, Communications Equipment etc.



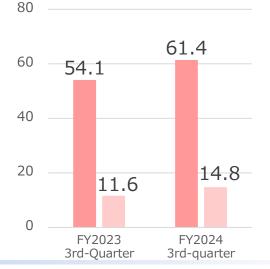
#### **Metal Packages**

	FY2023	FY2024	Yo	Υ
	3rd-Quarter*1 (Results)	3rd-Quarter* <sup>1</sup> (Results)	Amount	Ratio of Change
Net Sales	54.1 [34%]*2	61.4 [38%]*2	+7.3	+14%
Ordinary Profit	11.6 (21%)*3	14.8 (24%)*3	+3.2	+28%

<sup>\*1</sup> Nine months ended December 31 \*2 Represent % of Net Sales \* 3 Ratio against Net Sales

Net sales Ordinary Profit

- Orders of ceramic electrostatic chucks increased for semiconductor manufacturing equipment.
- Net sales of heat spreaders for CPUs grew due to increase in orders for servers.
- Net sales of glass-to-metal-seals were at almost the same level as the previous fiscal year for optical devices.
- Net sales of leadframes were at almost the same level as the previous fiscal year due to the progress of yen depreciation in the exchange rate and other factors, despite the impact of inventory adjustments for automobiles, etc.





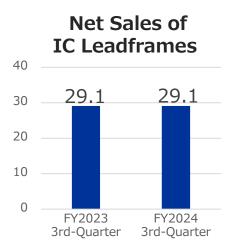
#### **Net Sales by Product Category**

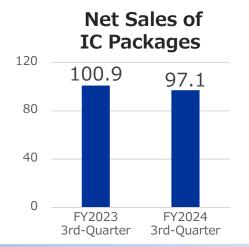
(Billions of yen)
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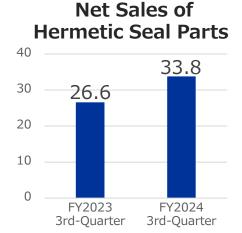
	FY2023	FY2024	YoY		
	3rd-Quarter* <sup>1</sup> (Results)	3rd-Quarter* <sup>1</sup> (Results)	Amount	Ratio of Change	
IC Leadframes	29.1 [19%]*2	29.1 [18%]*2	-0.0	-0%	
IC Packages	100.9 [64%]*2	97.1 [61%]*2	-3.8	-4%	
Hermetic Seal Parts	26.6 [17%]*2	33.8 [21%]*2	+7.1	+27%	

(Billions of yen)						
FY2023 (Results)						
38.9[18%]*2						
133.6[64%]*2						
37.5[18%]*2						

<sup>\*1</sup> Nine months ended December 31 \*2 Represent % of Net Sales









#### Revised Forecast (Announcement on January 31, 2025)

				<u> </u>			
	FY2024						
	Previous	Current	vs. Previous Forecast				
	Forecast (10/25/2024)	Forecast (1/31/2025)	Amount	Ratio of Change			
Net Sales	243.3	215.0	-28.3	-12%			
Operating Profit	40.7	25.6	-15.1	-37%			
Ordinary Profit	40.5	25.6	-14.9	-37%			
Profit*	27.2	18.0	-9.2	-34%			
Earnings per Share	201.31yen	133.22yen		-			

<sup>\*</sup> Profit attributable to owners of parent

- Reasons for the Revision of FY2024
- The situation remains tough, in which net sales of flip-chip type packages, plastic BGA substrates and leadframes fall short of the previous forecast of FY2024 due to the large impact of the prolonged inventory adjustments and other factors.
- Net sales remain to be lower than the previous forecast of FY2024 because flip-chip type packages' demand for servers remains sluggish longer than expected and the demand for PCs is affected by intensified competition, plastic BGA substrates saw a downturn in demand for advanced memory in FY2024 3Q, and leadframes continue to experience inventory adjustments, especially for automotive, and so on. Profits also remain below the previous forecast, significantly affected by the decline in net sales.

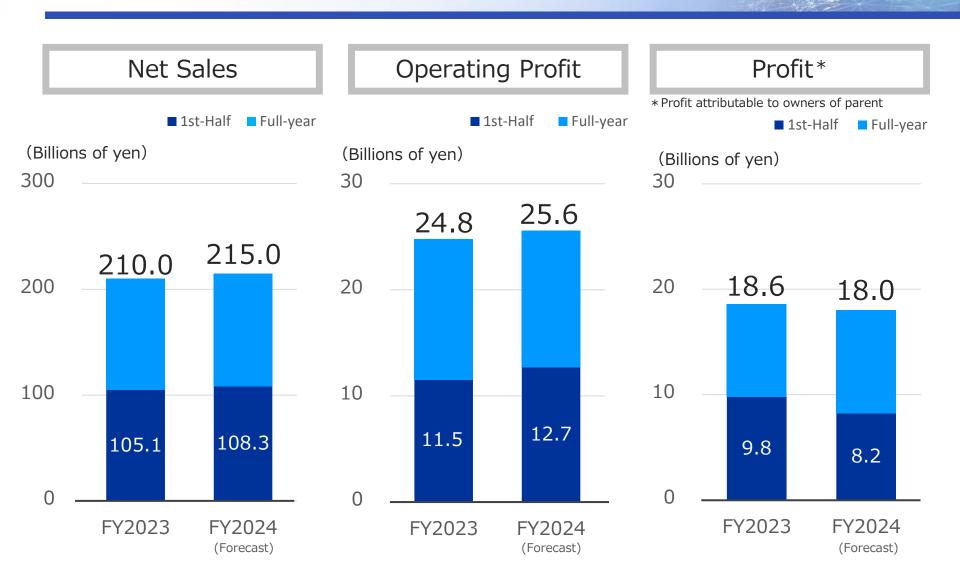


#### **Net Sales/Profit**

	FY2023 (Results)		FY2024 (1 <sup>st</sup> HF:Results·2 <sup>nd</sup> HF:Forecast)		YoY(Upper: Amount/Lower: Ratio of Change)					
	1 <sup>st</sup> Half	2 <sup>nd</sup> Half	FY 2023	1 <sup>st</sup> Half	2 <sup>nd</sup> Hal		FY 2024	1 <sup>st</sup> Half	2 <sup>nd</sup> Half	Full Year
Net Sales	105.1	104.9	210.0	108.3	106	5.7	215.0	+3.2 (+3%)	+1.8 (+2%)	+5.0 (+2%)
Operating Profit (Ratio against Net Sales)	11.5 (11%)	13.3 (13%)	24.8 (12%)	12.7 (12%)	12 (12	2.9 %)	25.6 (12%)	+1.3 (+11%)	-0.5 (-3%)	+0.8 (+3%)
Ordinary Profit (Ratio against Net Sales)	14.1 (13%)	13.2 (13%)	27.3 (13%)	11.6 (11%)	1 <sup>4</sup> (13	4.0 %)	25.6 (12%)	-2.5 (-18%)	+0.8 (+6%)	-1.7 (-6%)
Profit * (Ratio against Net Sales)	9.8 (9%)	8.8 (8%)		8.2 (8%)		9.8	18.0 (8%)	-1.6 (-16%)	+1.0 (+11%)	-0.6 (-3%)
Exchange Rates (Yen/US dollar)	143		_	Q-3Q 4Q 4Q (Assumption) 140						

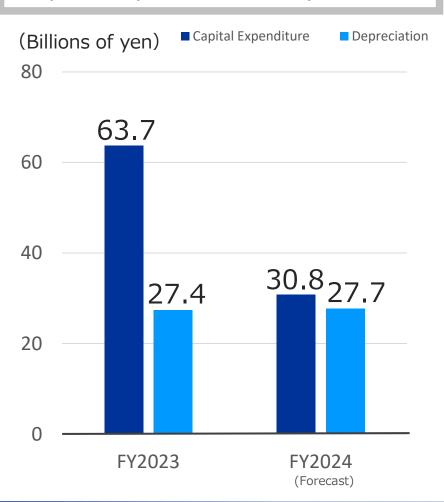
<sup>\*</sup> Profit attributable to owners of parent



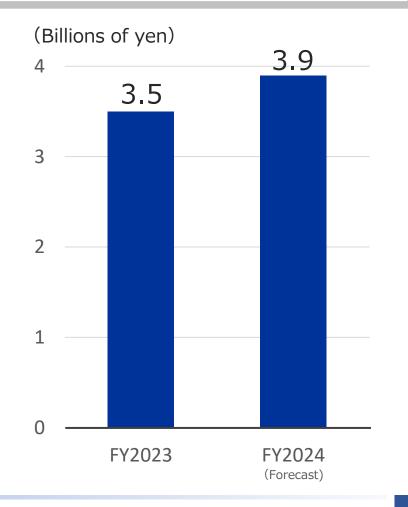




#### Capital Expenditure / Depreciation



#### Research and Development





## Progress of the Tender Offer for Company Shares by JICC-04, Ltd.

We announced the progress of this matter as follows on January 21, 2025.

#### (Progress of Disclosed Matters) Notice Concerning Progress of the Tender Offer for Company Shares (Securities Code: 6967) by JICC-04, Ltd.

The Company announced in its press release titled "Notice Concerning Expression of Opinion to Support Commencement of Tender Offer for Company Shares by JICC-04, Ltd. and Recommendation of Tender Thereto" dated December 12, 2023 (including subsequent corrections, the "Press Release dated December 12, 2023") that according to JICC-04, Ltd. (the "Tender Offeror"), it plans to commence a tender offer (the "Tender Offer") for the common shares of the Company on the condition that certain conditions precedent are satisfied, including the completion of all necessary procedures and steps under domestic and foreign competition laws and foreign investment control laws and regulations.

In addition, as announced in its press release titled "(Progress of Disclosed Matters) Notice Concerning Progress, etc. of the Tender Offer for Company Shares (Securities Code: 6967) by JICC-04, Ltd." dated August 26, 2024, the Company received notification from the Tender Offeror that it expects to commence the Tender Offer in or after late January 2025 because from among the procedures and steps necessary under the competition laws of Japan, South Korea, Vietnam, and China, the procedures and steps necessary under the competition laws of Vietnam and China have not been completed.

Following that, the Company received notification from the Tender Offeror that the Tender Offeror has completed the procedures and steps necessary under the competition laws of Vietnam on November 20, 2024, and has completed the procedures and steps necessary under the competition laws of China on December 27, 2024. As of January 21, 2025, taking into account the status of discussions among the relevant parties regarding the time required for the procedures to commence the Tender Offer, the Tender Offeror plans to commence the Tender Offer around mid February, 2025.

The Company will make an announcement promptly when the Company receives notification from the Tender Offeror that the Tender Offeror will commence the Tender Offer or there has been a change in the planned timing of commencement of the Tender Offeror mentioned above.



Notes to projected financial results:

The above projections were prepared based on estimates using information currently available. Actual results may differ from the projections. Also, many numerical values are shown in units of a billion yen as a general outline of business performance in this material. Because original values, which are managed in units of a million yen, are round off, the totals, difference, etc. shown in these materials may appear inaccurate. For assumptions and the other information regarding the projections, please refer to "the Financial Results" on IR library of our corporate website.